

Novel Packaging to Reduce Stray Inductance in Power Electronics

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Project ID: APE022

Overview

Timeline

- Start Date: Oct. 2009
- End Date: Sept. 2012
- 20% Complete

Budget

- DOE Share – 100%
- FY10 received: \$348K

Barriers

- Barriers:
 - Accurately measuring:
 - Module parasitics
 - Device stresses inside the module
 - Reduce side effect caused by added inductance for dead time minimization
 - Integration of the inductance into the trace.
- Target: Reduced voltage stress on IGBTs of the traction drive inverter.

Partners

- The University of Tennessee
- MaxQ Technology, LLC (module fabrication)

Objective

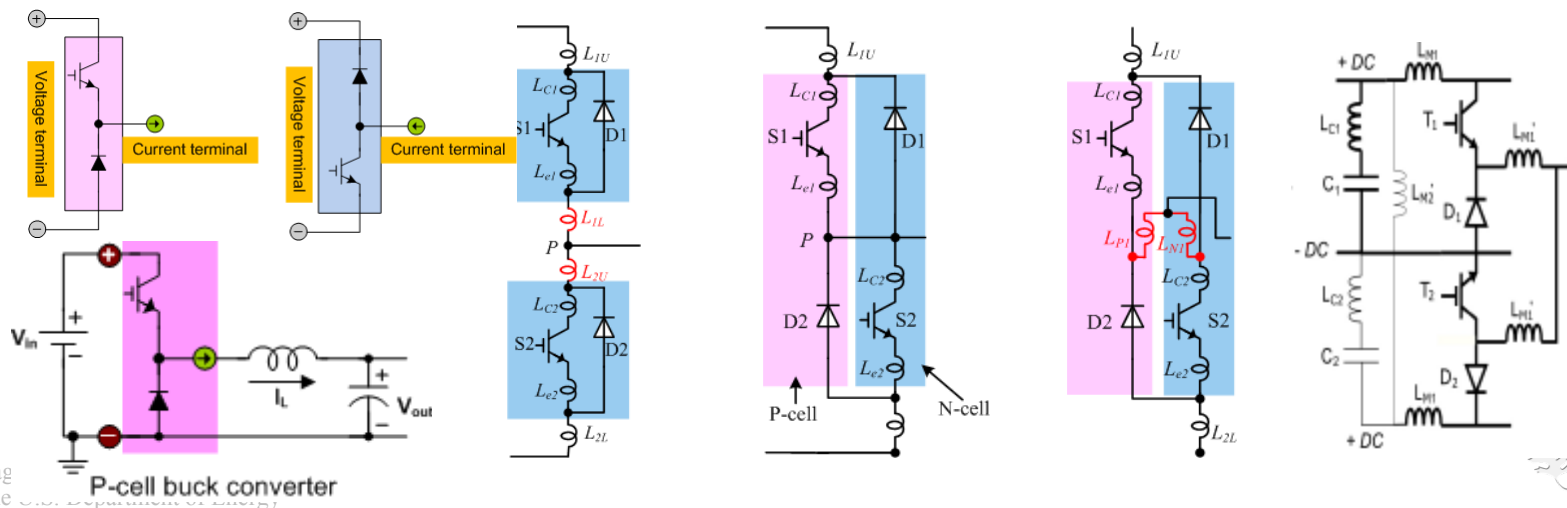
- Package devices in large power modules such that stray inductance is reduced.
 - Increase inverter reliability
 - Increase device capability, reduce inverter cost
- FY10
 - Extract parasitics in conventional and proposed power module using electromagnetic-field simulation tool
 - Model and simulate IGBT switching behavior with extracted parasitics
 - Build a prototype of a 10 kW IGBT single phase leg module using the proposed packaging method

Milestone

- **August 2010: Build phase leg module using proposed packaging method, measure and compare parasitics with conventional module.**
- *Go/No Go – If extracted parasitic inductance using Q3D extractor is smaller than conventional module, proceed.*

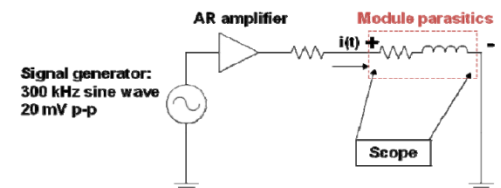
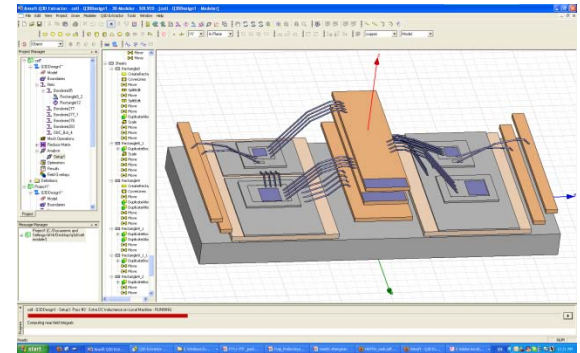
Approach and Strategy

- Series combination of switch and diode forms basic switching cells, N-cell and P-cell, which can be used to construct all commonly used DC-DC and DC-AC converters. Use p-cell and n-cell concept to change packaging technique. IGBT and diode are packaged in a series arrangement instead of anti-parallel.
- By adding inductors between a P-cell and N-cell in a phase leg, dead time requirement can be reduced.
- For inverter application, vertical layout of N-cell and P-cell could be exploited for further integration.



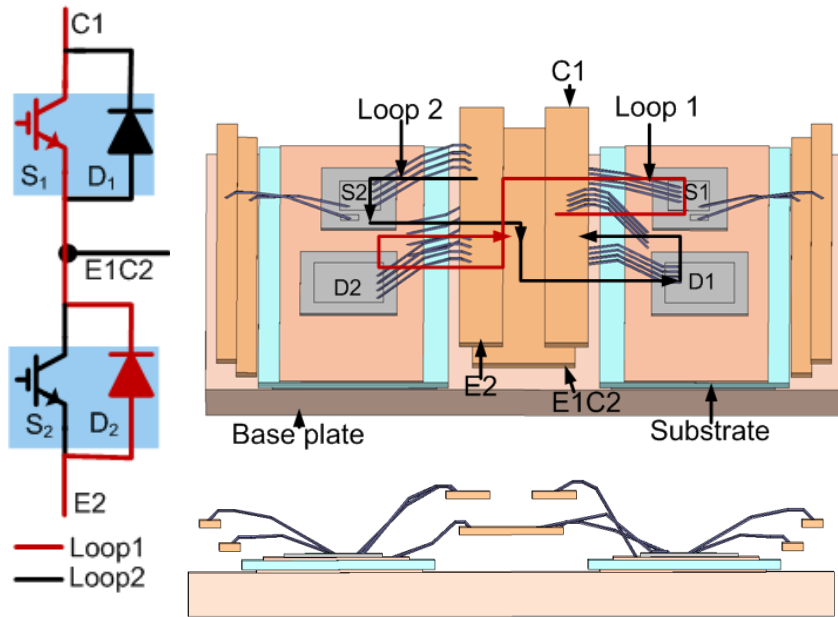
Approach and Strategy (cont'd)

- Ansoft Q3D extractor is used to perform electromagnetic-field simulation of package to extract parasitics.
- Saber is used for circuit simulation after getting the parasitic model.
- Prototype of proposed package will be built; impedance analyzer and V-I method will be used to measure the parasitics in P-cell and N-cell modules.

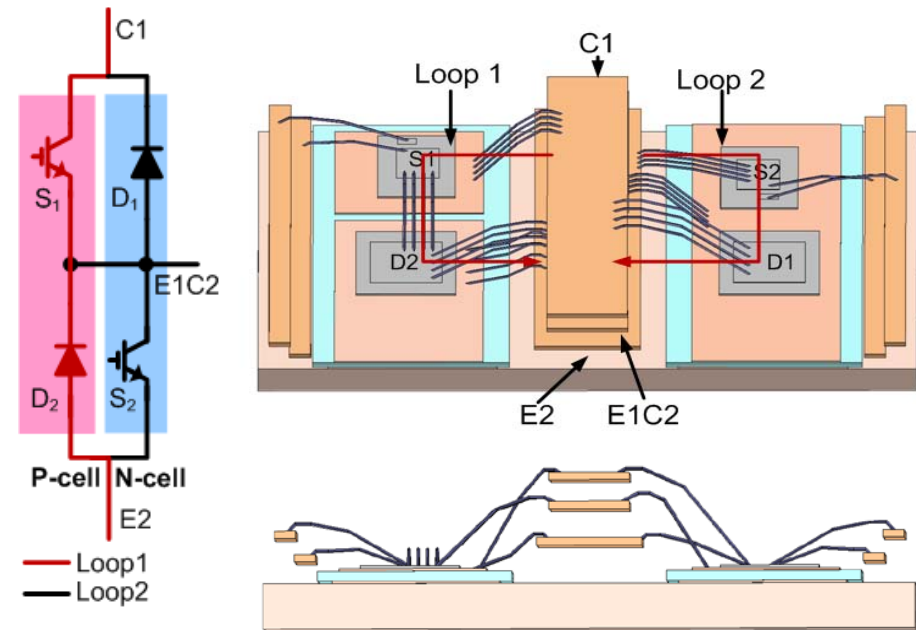


FY10 Technical Accomplishments

- Package for phase leg modeled using Ansoft Q3D Extractor



Conventional phase leg package



Proposed phase leg package

FY10 Technical Accomplishments (Cont'd)

- Extracted parasitic resistance and inductance

Conventional phase leg package

Loop 1: $R = 8.36\text{m}\Omega$, $L = 56.06\text{nH}$

Loop 2: $R = 7.81\text{m}\Omega$, $L = 52.67\text{nH}$

S_1 emitter to D_2 cathode:

$R = 3.18\text{m}\Omega$, $L = 22.19\text{nH}$

S_2 collector to D_1 anode:

$R = 3.24\text{m}\Omega$, $L = 23.36\text{nH}$

Proposed phase leg package

Loop 1: $R = 6.44\text{m}\Omega$, $L = 39.91\text{nH}$

Loop 2: $R = 5.62\text{m}\Omega$, $L = 36.18\text{nH}$

S_1 emitter to D_2 cathode:

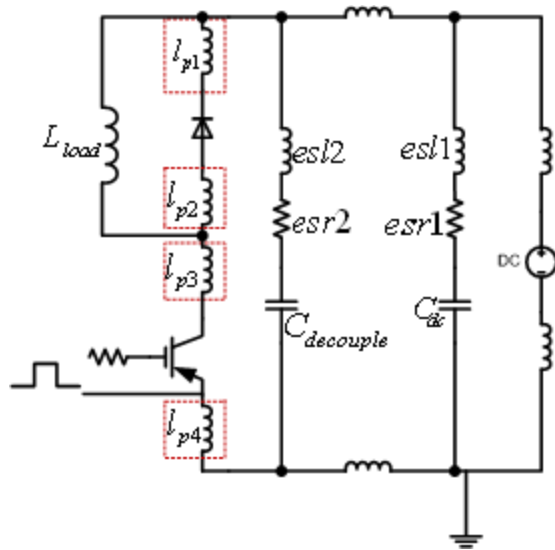
$R = 1.26\text{m}\Omega$, $L = 4.23\text{nH}$

S_2 collector to D_1 anode:

$R = 0.04\text{m}\Omega$, $L = 2.14\text{nH}$

FY10 Technical Accomplishments (Cont'd)

- Saber simulation is conducted using the parasitics extracted from Q3D



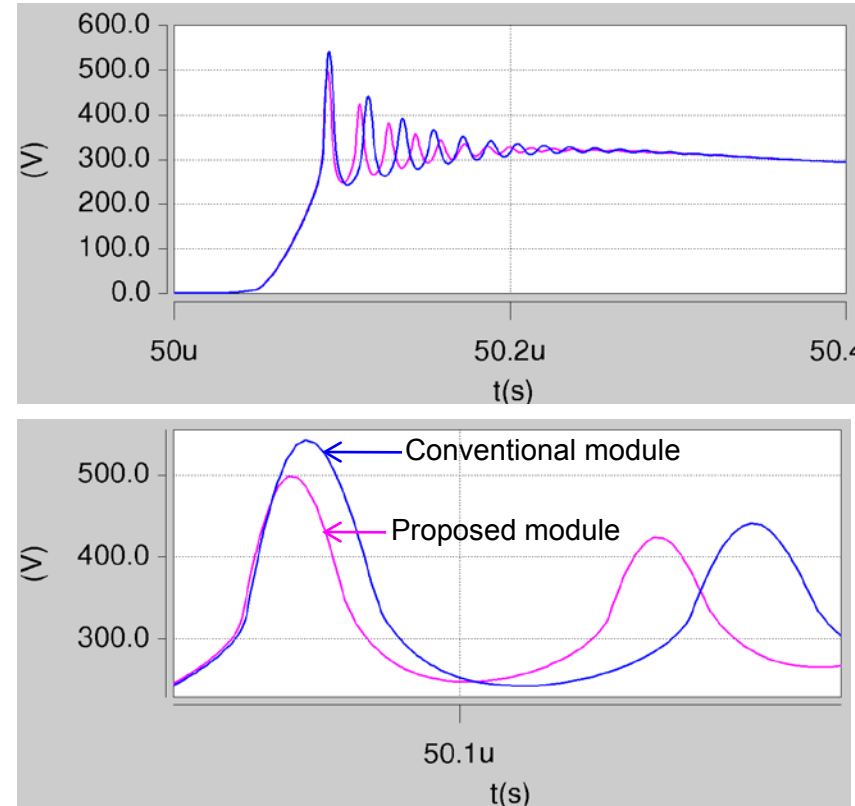
Double pulse test circuit

Parasitic Inductance Values

	Conventional module	Proposed module
l_{p1}	15.3 nH	17 nH
l_{p2}	11.4 nH	1.07 nH
l_{p3}	11.4 nH	1.07 nH
l_{p4}	15.3 nH	17 nH

FY10 Technical Accomplishments (Cont'd)

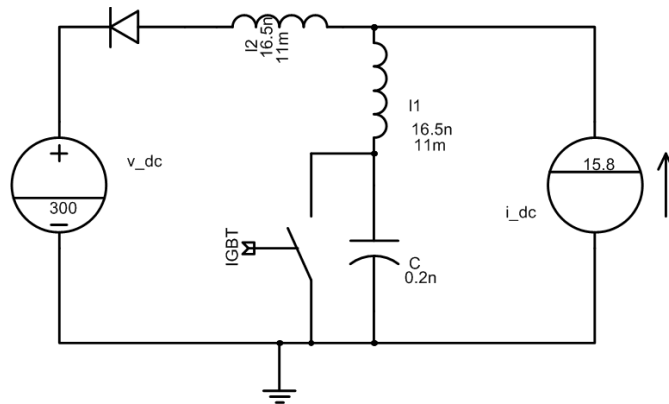
- Simulation results for turn off voltage
 - $\Delta V_{\text{conventional}} = 243 \text{ V}$
 - $\Delta V_{\text{proposed}} = 200 \text{ V}$



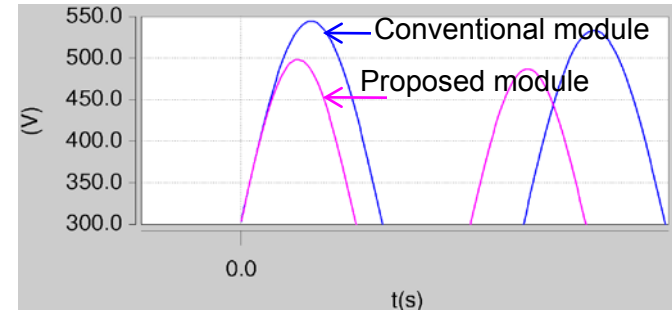
Turn off overshoot voltage

FY10 Technical Accomplishments (Cont'd)

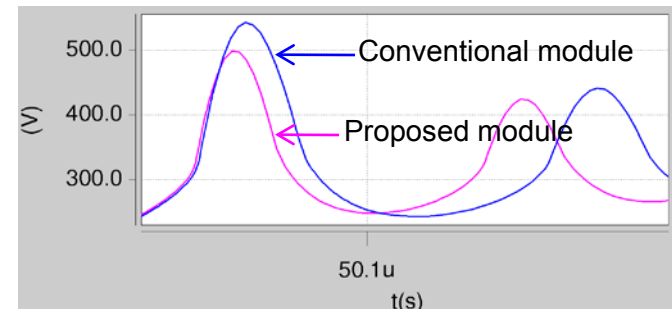
- **Modeling turn off overshoot voltage**
 - At turn off, there is an abrupt drop of current which causes the large voltage drop across the stray inductance.
 - Voltage across IGBT increases
 - IGBT parasitic capacitance will be charged



Circuit model



Overshoot voltage of the model



Overshoot voltage of the double pulse test

Collaborations

- Partners:
 - The University of Tennessee (Academic): Collaborate for development.
 - MaxQ Technology, LLC (Industry): Collaborate to fabricate the power module.

Future Work – FY10

- **Model turn off voltage overshoot and turn on current ringing in a power module with parasitics**
- **Build a prototype of a 10 kW IGBT single phase leg module using the proposed packaging method**
- **Measure parasitic inductance and resistance, compare with simulation results**

Future Work – FY11 and beyond

- **Build a converter using P-cell and N-cell packaging method to test and compare the electrical characteristics**
 - **Measure and compare voltage spikes across the device**
 - **Compare the rise and fall time performance**
 - **Calculate the power loss reduction due to the novel package**
- **Add inductors between P-cell and N-cell to minimize dead-time requirement**
 - **Simulation study on inductor value selection**
 - **Build an inverter prototype to verify the simulated results**
 - **Integrate the inductors into the packaged module**
- **Model, simulate and build vertical (without wire bond) power module using planar technology and double sided cooling**

Summary

- **New packaging method based on P-cell and N-cell is proposed to reduce the stray inductance between the active switch (IGBT) and diode.**
- **Electromagnetic and circuit simulation shows reduction of parasitic inductance (20% reduction) and resistance, and corresponding improvement in overshoot voltage in the proposed package module (15% reduction).**
- **A 10 kW phase leg power module is being developed that incorporates the novel circuit layout.**